

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-2. (Cancelled)

3. (Currently Amended) The resin substrate having a resin-metal composite layer set forth in claim ~~[[1]]~~ 6, wherein said resin-metal composite layer is a transparent conductive layer which is 200 nm or less ~~than 200 nm~~ in thickness.

4. (Withdrawn) A method for manufacturing a resin substrate having a resin-metal composite layer at a surface thereof, comprising:

a pretreatment process that a surface of the resin substrate is modified to a modified layer having a polar group, and

an adsorbing process that at least either metal colloids or ions are adsorbed to the polar group by contacting the modified layer with a metal compound solution, whereby metal particles are dispersed into the modified layer.

5. (Withdrawn) A method for manufacturing a resin substrate having a resin-metal composite layer at a surface thereof set forth in claim 4, wherein after said adsorbing process, a metal coating is formed on the surface of said modified layer by electroless plating, thereafter remove said metal coating.

6. (New) A resin substrate having a resin-metal composite layer on a surface of the resin substrate, the resin-metal composite layer comprising reduced metallic particles dispersed in a resin matrix,

wherein the resin-metal composite layer is from 20 to 2000 nm in thickness; and the concentration of the metallic particles is from 20 to 90%(v/v) in the resin-metal composite layer.

7. (New) The resin substrate having a resin-metal composite layer set forth in claim 6, wherein the metallic particles comprise metal particles selected from the group of precious metals.